

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1913	(257/690).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/10 08:00
L2	25	(electrical\$4 near path) near8 (test\$4 near pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 08:06
L3	33	1 and (test\$4 near pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 08:10
L4	390	(die element device component chip IC "integrated near circuit") near8 (inactive same active) same (test or testing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 08:54
L5	4031	(die element device component chip IC "integrated near circuit") same inactive same (test or testing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 08:55
L6	573	5 and (probe or probed or probing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 08:57
L7	429	6 and ((@ad<"20020122") or (@rlad<"20020122"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 09:46
L8	0	(test near pad) near4 (inactive near surface) same (die element chip IC component device dice)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 09:47

## EAST Search History

L9	0	(test near pad) near4 (inactive near surface) and (die element chip IC component device dice)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 09:47
L10	8	(test near pad) near4 (inactive) and (die element chip IC component device dice)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 09:49
L32	13	("3401126"   "3429040"   "4472876"   "4763409"   "4866508"   "5008614"   "5036380"   "5042147"   "5148265"   "5148266"   "5156983").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/10 10:46
L33	2	(test near pad) near8 outside near4 active	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/10 10:49
L34	2762	(438/612).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/10 10:50